



**MULTILAYER CERAMIC BALUN  
FOR BLUETOOTH & WLAN IEEE 802.11b/g (2.45GHz ISM Band)**

**Product Specification<sup>1</sup>**

QUICK REFERENCE DATA

**Specifications**

|   |   |
|---|---|
| Frequency Range                           | 2400-2500 MHz   |
| Unbalanced Impedance                      | 50 Ohm  |
| Balanced Impedance                        | 100 Ohm   |
| Unbalanced port V.S.W.R.<br>(Return Loss) | 2.0 (Max)<br>10dB (Min)                                     |
| Insertion Loss                            | 1 dB (Max) at 25 Deg. C<br>1.3 dB (Max) at -40 ~ +85 Deg. C |
| Ripple                                    | 0.6Db   |
| Phase Difference                          | 180 ±10 degree  |
| Amplitude Difference                      | 2.0 dB (Max)  |
| Dimension                                 | 2.0 x 1.25 x 0.8 mm   |

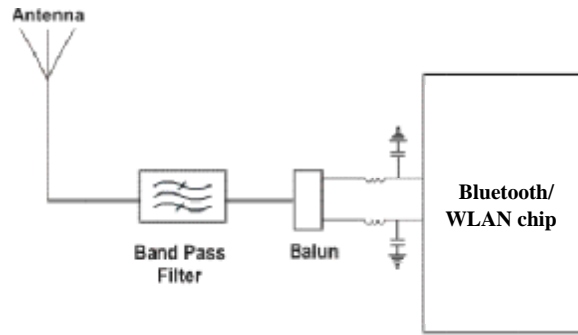


*Special Environmental Concerns- Green Products Design: Termination is lead free (Pb free) and packing materials can be re-cycled*

<sup>1</sup> All the technical data and information contained herein are subject to change without prior notice

|  |           |                 |             |                    |                  |            |   |               |        |                |
|--|-----------|-----------------|-------------|--------------------|------------------|------------|---|---------------|--------|----------------|
| 2012/2.45GHz 50-100ohm<br>Multilayer Ceramic Balun |           |                 |             | CBA4711714012454K, |                  |            |   | —<br>▶        | 6      | March,<br>2005 |
| BY / 製定者   | J.S.Hsieh | SUPER /<br>原圖編號 | C.T.<br>Lee | TLL.SH<br>/ 共頁     | 12               | PAGE/<br>頁 | 2 | SH nr.<br>190 | —<br>▶ |                |
| CHECK  |           |                 |             | DATE / 日期          | 4th, April. 2005 |            |   | —<br>▶        |        |                |

## Applications



## Dimensions and Port Configurations

| Figure | Dimension  | Port  |
|--------|--|---|
|        | <p>L 2.0±0.15mm</p> <p>W 1.25±0.15mm</p> <p>T 0.8±0.15mm</p> <p>P1 0.3±0.15mm</p> <p>P2 0.3±0.15mm</p> <p>P3 0.3±0.15mm</p> <p>P4 0.3±0.15mm</p> <p>P5 0.3±0.15mm</p> <p>P6 0.3±0.15mm</p> <p>D1 0.2±0.15mm</p> <p>D2 0.65±0.15mm</p> <p>D3 0.35±0.15mm</p> <p>D4 0.3±0.15mm</p> | <p>Unbal. Port</p> <p>Ground or DC</p> <p>Balanced Port</p> <p>Balanced Port</p> <p>Ground</p> <p>Not Connect</p> |

|  |           |                    |             |                |                  |            |                |
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| CHECK  |           |                    |             | DATE / 日期      | 4th, April. 2005 |            |                |

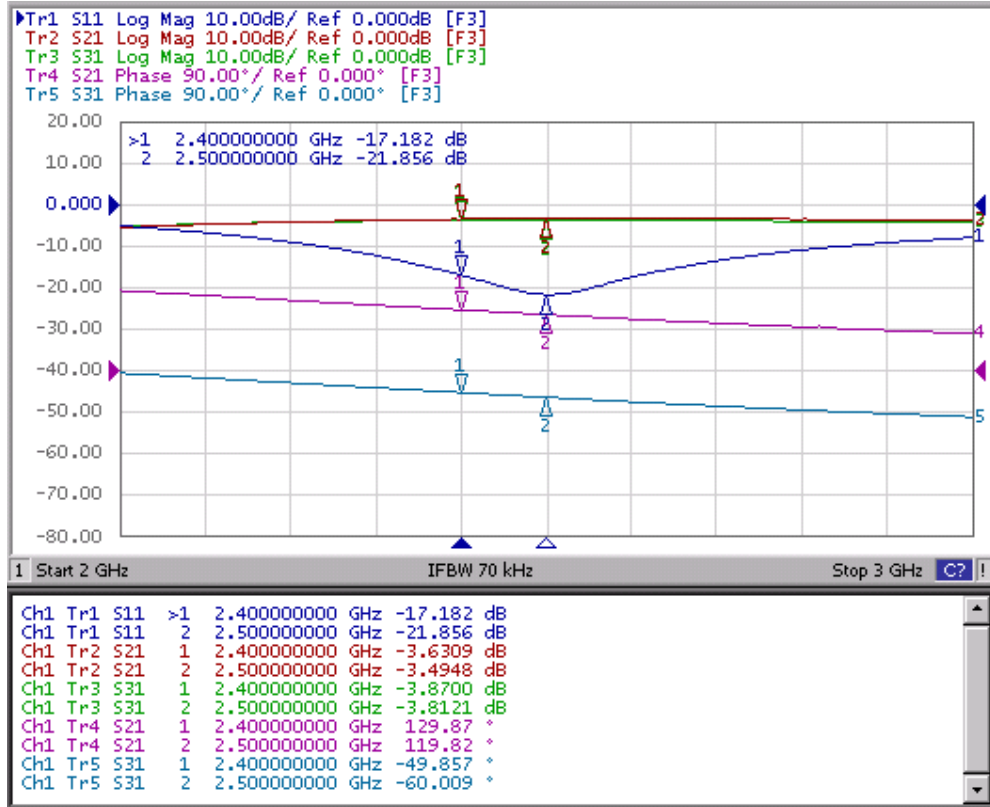
**Recommended PCB Pattern**

| Figure | Dimension  |  | Remark               |
|--------|--|--|----------------------|
|        | D1<br>D2<br>D3<br>D4<br>D5<br>D6<br><br>Land<br>Through hole | 1.0 ±0.1mm<br>0.8 ±0.1mm<br>0.35 ±0.1mm<br>0.65 ±0.1mm<br>0.25 ±0.1mm<br>0.25 ±0.1mm | Land<br>Through hole |

|  |                  |                 |             |                           |                  |               |        |          |                |
|--|------------------|-----------------|-------------|---------------------------|------------------|---------------|--------|----------|----------------|
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|  |                  |                 |             |                           |                  |               |        | —<br>▶   |                |
|  |                  |                 |             |                           |                  |               |        | —<br>▶   |                |
| BY / 製定者   | <b>J.S.Hsieh</b> | SUPER /<br>原圖編號 | C.T.<br>Lee | TLL.SH<br>/ 共頁 12         | PAGE/<br>頁 4     | SH nr.<br>190 | —<br>▶ |          |                |
| CHECK  |                  |                 |             | DATE / 日期                 | 4th, April. 2005 |               |        | —<br>▶   |                |

## Frequency Characteristics (I)

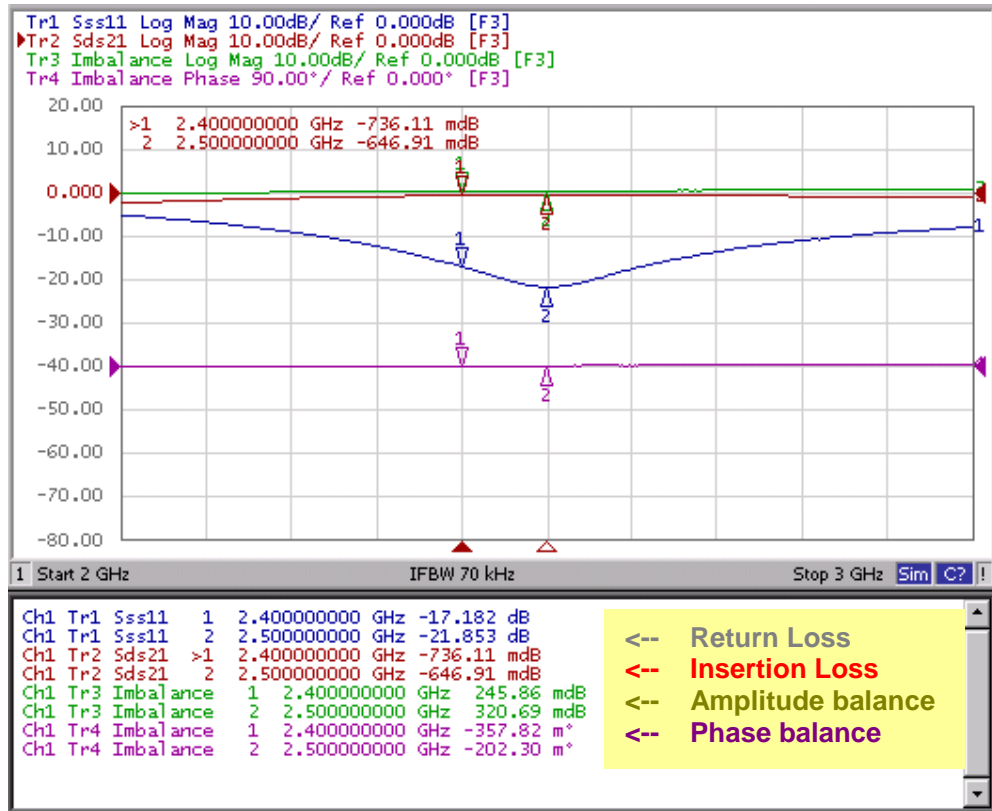
### S11, S21, S31 Measured on Agilent E5071A Network Analyzer



|  |           |                    |             |                |                  |            |             |               |
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## Frequency Characteristics (II)

**Insertion loss (Sds21, differential port to single-ended port) and Imbalance (S21/S31 amplitude and phase difference) measured on Agilent E5071A Network Analyzer**



|  |           |                    |             |                    |                  |            |   |               |                |
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| CHECK  |           |                    |             | DATE / 日 期         | 4th, April. 2005 |            |   |               |                |

**RELIABILITY DATA (Reference to IEC Specification)**

| IEC 384-10/<br>CECC 32<br>100<br>CLAUSE | IEC 60068-2<br>TEST<br>METHOD | TEST                                  | PROCEDURE   | REQUIREMENTS   |
|---|-------------------------------|---------------------------------------|---|--|
| 4.4                                     |                               | Mounting                              | The balun can be mounted on printed-circuit boards or ceramic substrates by applying wave soldering, reflow soldering (including vapour phase soldering) or conductive adhesive | No visible damage  |
| 4.5                                     |                               | Visual inspection and dimension check | Any applicable method using $\times 10$ magnification   | In accordance with specification (chip off 1mm)            |
| 4.6.1                                   |                               | Balun                                 | VSWR < 2 at 20 °C   | Standard test board  |
| 4.8                                     |                               | Adhesion                              | A force of 3 N applied for 10 s to the line joining the terminations and in a plane parallel to the substrate   | No visible damage  |
| 4.9                                     |                               | Bond strength of plating on end face  | Mounted in accordance with CECC 32 100, paragraph 4.4   | No visible damage  |
|   |                               |                                       | Conditions: bending 0.5 mm at a rate of 1mm/s, radius jig. 340 mm, 2mm warp on FR4 board of 90 mm length  | No visible damage  |
| 4.10                                    | 20(Tb)                        | Resistance to soldering heat          | 260 $\pm$ 5 °C for 10 $\pm$ 0.5 s in a static solder bath   | No visible damage and complies with electrical performance |

|  |           |                 |             |                    |                  |            |   |               |   |             |
|--|-----------|-----------------|-------------|--------------------|------------------|------------|---|---------------|---|-------------|
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|  |           |                 |             |                    |                  |            |   |               | ▶ |             |

| IEC 384-10/CECC 32100 CLAUSE | IEC 60068-2 TEST METHOD | TEST                        | PROCEDURE  | REQUIREMENTS  |
|------------------------------|-------------------------|-----------------------------|--|---|
|                              |                         | Resistance to leaching      | 260 ± 5 °C for 30 ± 1 s in a static solder bath  | Using visual enlargement of × 10, dissolution of the termination shall not exceed 10% |
| 4.11                         | 20(Ta)                  | Solderability               | Zero hour test, and test after storage (20 to 24 months) in original atmosphere; un-mounted chips completely immersed for 2 ± 0.5 s in 235 ± 5°C.  | The termination must be well tinned, at least 75% is well tinned at termination       |
| 4.12                         | 4(Na)                   | Rapid change of temperature | -40 °C (30 minutes) to +85 °C (30 minutes); 200 cycles   | No visible damage and complies with electrical performance                            |
| 4.13                         | IEC 60384-10            | Climate sequence            | 1. Initial measurement<br>2. Dry Heat (16hours, 85deg. C)<br>3. Damp heat, cycle, Test Db first cycle (24hours; 55deg.C; 95 to 100% R.H.)<br>4. Cold(-20deg.C, 2hours)<br>5. Damp heat, cycle, Test Db, remaining<br>6. Final measurements | No visible damage and complies with electrical performance                            |
| 4.14                         | 3(Ca)                   | Damp heat                   | 500 ± 12 hours at 40 °C; 90 to 95 % RH   | No visible damage and complies with electrical performance                            |
| 4.15                         |                         | Endurance                   | 500 ± 12 hours at 85 °C;   | No visible damage and complies with electrical performance                            |

|   |           |              |          |                    |                  |         |   |            |   |             |
|---|-----------|--------------|----------|--------------------|------------------|---------|---|------------|---|-------------|
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|   |           |              |          |                    |                  |         |   | ▶          |   |             |
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| CHECK   |           |              |          | DATE / 日期          | 4th, April. 2005 |         |   | —          |   |             |

**ORDERING INFORMATION:**

These code numbers can be determined by the following rules:

4711 7 14 01 245  
F C M S T A

F. Family Code

**47** = Balun

C. Packing Type Code

**11** = 180 mm/ 7" blister

M. Materials Code

**7** = High Frequency Material

S. Size Code

**11** = 3.2 \* 2.5

**12** = 3.2 \* 1.6

**13** = 2.5 \* 2.0

**14** = 2.0 \* 1.2

**15** = 1.6 \* 0.8

T. Type

**00** = Unbalanced and balanced impedance, Type 1: 50 Ohm –50 Ohm

**01** = Unbalanced and balanced impedance, Type 2: 50 Ohm –100 Ohm

**02** = Unbalanced and balanced impedance, Type 3: 50 Ohm –200 Ohm

A. Working Frequency

**245** = 2.45 GHz

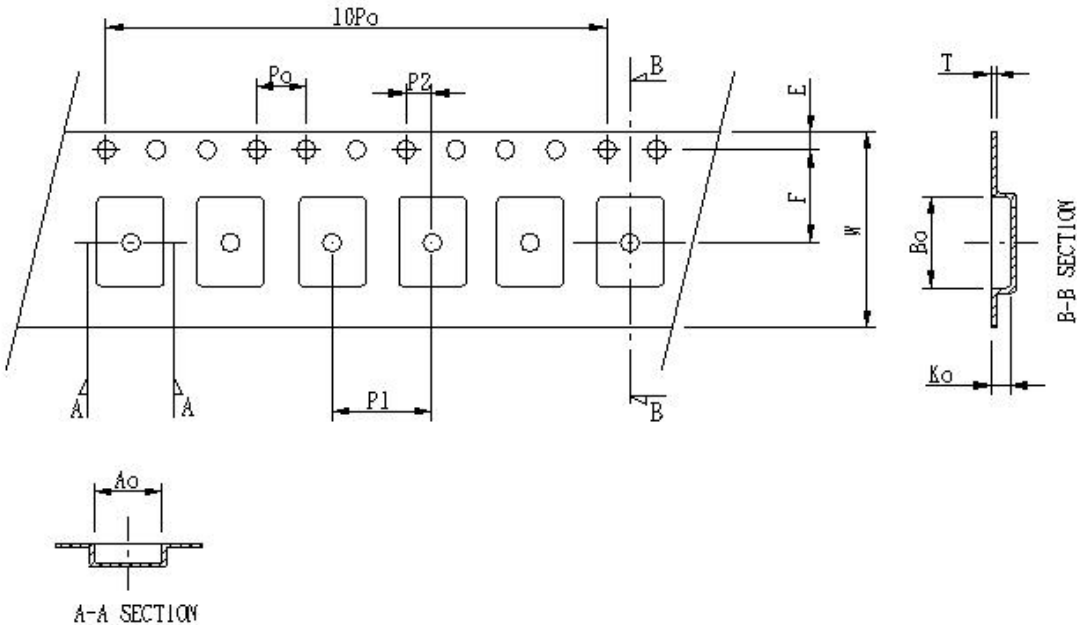
**ORDERING INFORMATION: Method - by Clear Text Code**

The baluns may be ordered by using the 17-digit clear text ordering code. These code numbers can be determined by the following rules:

| CBA4711714012454K (Clear Text Code Example) |              |               |                |                  |                   |            |              |
|---|--------------|---------------|----------------|------------------|-------------------|------------|--------------|
| CBA47                                       | 11           | 7             | 14             | 01               | 245               | 4          | K            |
| Product                                     | Packing type | Material      | Size           | Type             | Central Frequency | Quantities | Packing      |
| CBA47= Balun                                | 180mm/7"     | LTCC material | 14=2.0*1.25 mm | 01= 50-100 Balun | 245=2.45GHz       | 4= 4K pcs  | K=7" plastic |

|  |           |              |          |                    |                  |         |   |            |   |             |
|--|-----------|--------------|----------|--------------------|------------------|---------|---|------------|---|-------------|
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|  |           |              |          |                    |                  |         |   |            | ▶ |             |

**Taping Blister Tape**

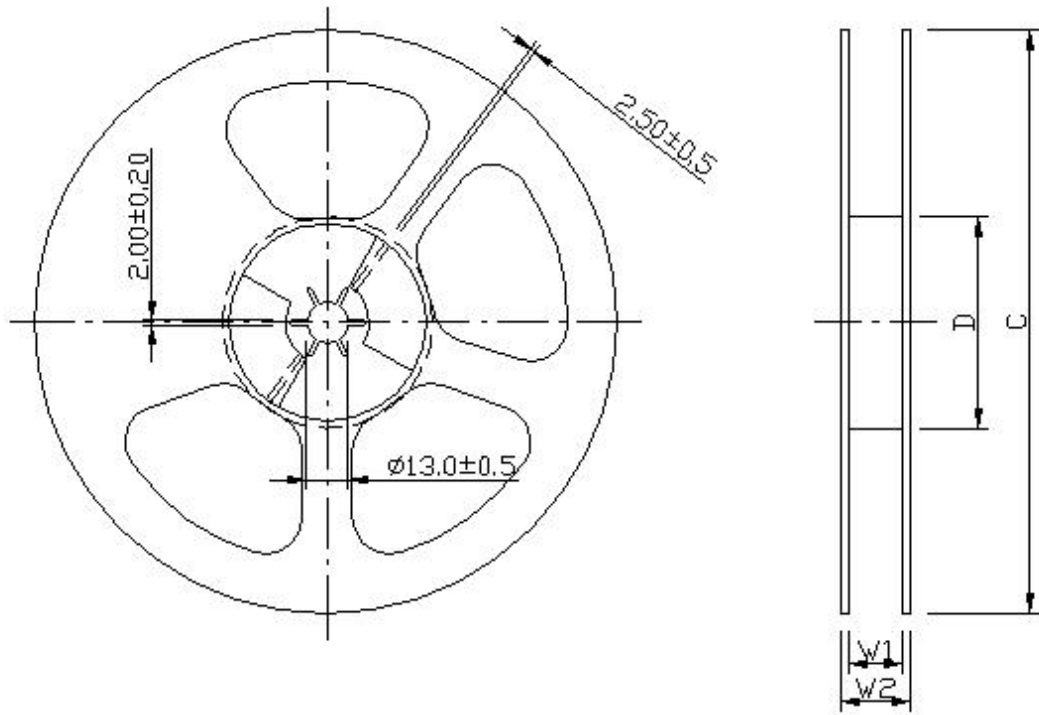


**DIMENSION:**

| Serial no | Cecking note                         | Index | Spec(mm)  |
|-----------|--------------------------------------|-------|-----------|
| 1         | Sprocket hole                        | Do    | 1.50±0.10 |
| 2         | Pocket hole                          | D1    | ≥1        |
| 3         | Distance sprocket hole/sprocket hole | Po    | 4.0±0.10  |
| 4         | Distance pocket/pocket               | P1    | 4.0±0.10  |
| 5         | Distance sprocket hole/pocket        | P2    | 2.0±0.10  |
| 6         | Tape width                           | W     | 8.1±0.20  |
| 7         | Distance sprocket hole/outside       | E     | 1.75±0.10 |
| 8         | Distance sprocket hole/pocket        | F     | 3.5±0.05  |
| 9         | Pocket length nominal clearance      | Ao    | 1.42±0.10 |
| 10        | Pocket length nominal clearance      | Bo    | 2.24±0.10 |
| 11        | Pocket depth minimum clearance       | Ko    | 1.04±0.10 |
| 12        | Thickness of tape                    | T     | 0.22±0.05 |
| 13        | 10x sprocket hole pitch              | 10Po  | 40.0±0.20 |

|  |           |                    |             |                 |                  |            |    |                |
|--|-----------|--------------------|-------------|-----------------|------------------|------------|----|----------------|
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|  |           |                    |             |                 |                  |            |    | ▶              |

**7"(180mm) Reel Specifications**



| Product size code | Units per Reel | Tape Width (mm) | C (mm)    | D (mm) | W <sub>1</sub> (mm) | W <sub>2</sub> (mm) |
|-------------------|----------------|-----------------|-----------|--------|---------------------|---------------------|
| Balun             | 4000           | 8               | 180.0±1.0 | 62±1.5 | 8.4+/-0.15          | 14.4 max            |

|  |  |  |  |                    |  |             |  |                    |   |                |  |               |  |   |
|--|--|--|--|--------------------|--|-------------|--|--------------------|---|----------------|--|---------------|--|---|
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**Revision Control:**

| Revision | Date                      | Content   | Remark |
|----------|---------------------------|---|--------|
| 1        | Feb. 12, 03               | New issued K7 5050 and 50100<br>5050: 4711 714 00 245<br>50100: 4711 714 01 245 |        |
| 2        | Apr. 14, 03               | Frequency characteristics re-drawn (on ENA)                                     |        |
| 3        | May 23, 03                | Thickness T=0.8+-0.15 mm  |        |
| 4        | Aug 06, 03                | 50200 added, electrical specs. updated  |        |
| 5        | 9 <sup>th</sup> Jan. 2004 | Modify format of data sheet   |        |
| 6        | March. 2005               | Modify and add "B2" mark  |        |

|  |  |           |                 |                    |                |                  |            |    |               |                |
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